Heraeus

Technical Data Sheet

MICROBOND®

Product Type: No Clean Solder Paste
Product Name: Microbond® SMT911
Product ID: SOP 91121 Innolot®-89M3

Description

SOP 91121 Innolot®-89M3 solder paste is a lead free no clean solder paste that promotes outstanding wetting and minimizes soldering defects. The SOP 91121 flux system is specifically optimized for lead free alloys, e.g. Sn/Ag/Cu. This formula provides superior performance on a variety of surfaces finishes and leaves behind a clear residue. The flux is designed to comprise with J-STD-004 L0 classification. **Reflow under N_2 is recommended.**

Key Benefits

- Exceptional print to print consistency
- Min. 8 hours tack and work life

Applications

- Printing

Product Code and Alloy

Product Code					Powder Properties		
Paste	Alloy	Metal Content	*Viscosity	Powder Type	Particle Size	Alloy	Melting Point
SOP 91121	Innolot®	89%	M	3	25 – 45 µm	Sn/Ag3.8/Cu0.7/ Ni0.15/Sb1.5/Bi3	206 - 218 °C

*D = Dispense grade M = Print grade H = Print grade, high L = Dipping/Jetting grade, Low

Flux Activity

Activity Level (J-STD 004)	ISO 9454-1 [DIN EN 29454-1]	Siemens Norm [SN 59650]	Classification
REL0	1.2.2.C	Static qualification passed	No Clean/ Solvent Clean

Halogen Content

Halogen-Containing

Tolerances: Cl or Br > 900 ppm, total > 1500 ppm; measured according to BS EN 14582

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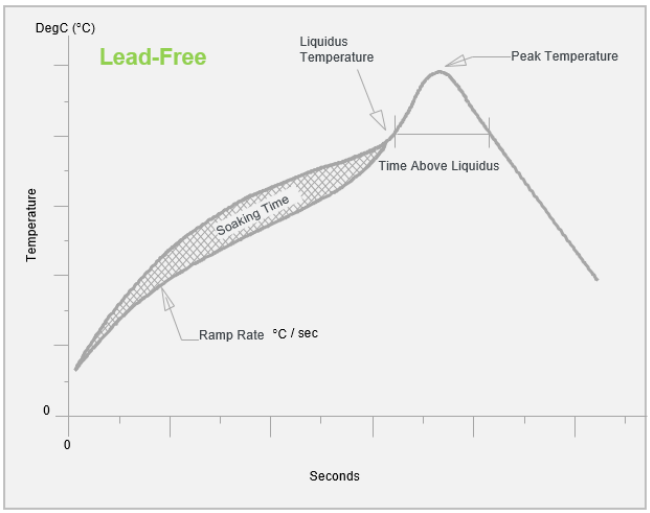
Recommended Reflow Profile



* Graph not drawn to scale

Recommended Profile	
Average Ramp Rate	**1 – 3 °C/s**
Peak Temperature	**15 °C (min) – 40 °C (max) above Melting Temperature**
Time above liquidus	**45 – 90 s**
Reflow Atmosphere Type 3 – 5	**Reflow under N_2**

The descriptions and engineering data shown here have been compiled by Heraeus using commonly-accepted procedures, in conjunction with modern testing equipment, and have been compiled as according to the latest factual knowledge in our possession. The information was up-to date on the date this document was printed (latest versions can always be supplied upon request). Although the data is considered accurate, we cannot guarantee accuracy, the results obtained from its use, or any patent infringement resulting from its use (unless this is contractually and explicitly agreed in writing, in advance). The data is supplied on the condition that the user shall conduct tests to determine materials suitability for a particular application)

Cleaning Instructions

After reflow flux residues may remain on the circuit and do not need to be washed. For cleaning of wet paste or if desired for cleaning of flux residues Zestron and Vigon cleaners can be used – see separate cleaning recommendations.

Storage

- Store the solder paste in tightly-sealed containers and avoid exposure to sunlight and high humidity
- Max expiration date: please refer to the expiry date on the label of the packaged product
- Storage condition in the refrigerator at 2 - 10 °C
- Store cartridges with tip pointing downwards

Paste Preparation

- Remove paste from fridge: Before opening the package, leave paste for at least 4 hours (depending on jar/ cartridge size) at room temperature, so that paste warms up
- Do not open jar/cartridge while paste is cold to prevent condensation
- Do not heat the paste beyond room temperature
- Before using paste jar: To obtain uniform, stable viscosity stir paste for 1 – 2 min, using stainless steel or chemically resistive plastic spatula
- Caution: When automatic stirring equipment is used, do not stir the paste longer than 2 min

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